<<TITEL>>

<<Name>>1, <<Name>>2

1 <<Company 1>>  
2 <<Company 2>>

Presenter: <<Name of Presenter>>  
E-mail: <<email>>

Presentation (oral and/or poster):

TOPIC:  
Please select one or more fitting topic(s) for your contribution from the list. (1=first, 2=second etc. choice)

|  |  |  |
| --- | --- | --- |
| Process Level APC  🗆 Plasma etch,CVD and ALD  🗆 Sputtering, P3I, and e--beam  🗆 Lithography  🗆 Thermal, wet processing & CMP  🗆 Backend  🗆 Metrology and R2R  🗆 APC for legacy tools | Fab Level APC  🗆 Fab level process control methods  🗆 Virtual metrology  🗆 Yield management  🗆 Factory data analysis  🗆 IT infrastructure | Manufacturing Effectiveness and Productivity  🗆 Unit process & equipment productivity  🗆 Factory productivity and automation  🗆 Factory modeling, simulation and optimization  🗆 Cost optimization and end-of-life equipment issues  🗆 Environment and Green Manufacturing |

## Motivation

<<TEXT>>

## Description

<<TEXT>>

## Innovation

<<TEXT>>

## Results

<<TEXT>>